

### AMENDMENTS TO THE CLAIMS

1-25 (Canceled)

26. (Currently Amended) A method for manufacturing a ceramic device using a mixture with photosensitive resin comprising the steps of:

providing a metal substrate;

forming a piezoelectric/electrostrictive layer on said metal substrate using a mixture of photosensitive resin and piezoelectric/electrostrictive ceramic;

masking and exposing said piezoelectric/electrostrictive layer to pattern ~~it~~ the piezoelectric/electrostrictive layer;

forming an upper electrode on said piezoelectric/electrostrictive layer using a mixture of photosensitive resin and metal; and

masking and exposing said upper electrode to pattern it.

27. (Currently Amended) The method in Claim 26, further comprising the step of thermally treating the ~~produced~~ ceramic device at 200-500°C.

28. (Previously Presented) The method in Claim 26, wherein said metal substrate is nickel or stainless steel.

29. (Currently Amended) The method in Claim 26, wherein said mixture of photosensitive resin and piezoelectric/electrostrictive ceramic is one of a ceramic sol solution containing photosensitive complexing agent, a mixture of ultraviolet ray hardening resin and ceramic powder, a mixture of

said mixture of a ultraviolet ray hardening resin and ceramic powder ~~and a ceramic sol solution of same or similar composition with said ceramic powder~~, or a mixture prepared by additional mixing of an organic solvent or controlling ~~the~~ a material property into said mixture of ultraviolet ray hardening resin and ceramic powder ~~a ceramic sol solution of same or similar composition with said ceramic powder~~.

30. (Currently Amended) The method in Claim 26, wherein said photosensitive resin to form a the mixture with the metal is a conductive UV adhesive or a transformed material of organic compound making a chelate with said metal.